

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

ON Semiconductor®

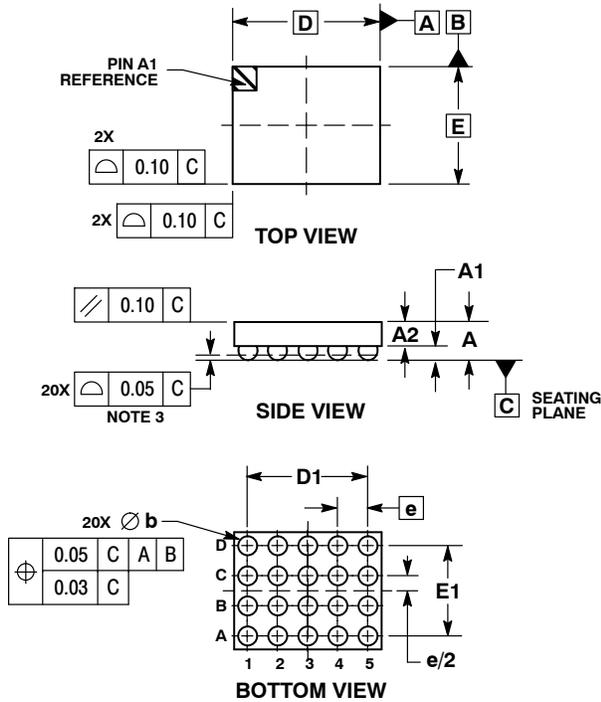


A1

SCALE 4:1

20 PIN FLIP-CHIP, 2.54x2.03, 0.5P CASE 766AK-01 ISSUE A

DATE 16 JUL 2010



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	---	0.66
A1	0.21	0.27
A2	0.33	0.39
b	0.29	0.34
D	2.54 BSC	
D1	2.00 BSC	
E	2.03 BSC	
E1	1.50 BSC	
e	0.50 BSC	

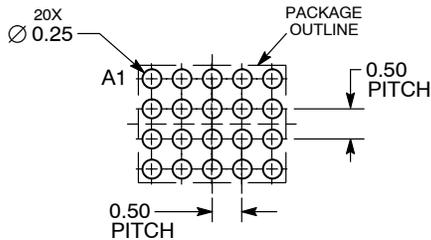
GENERIC MARKING DIAGRAM*



- XXXXXX = Specific Device Code
- A = Assembly Location
- Y = Year
- WW = Work Week
- = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present.

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	20 PIN FLIP-CHIP, 2.54 X 2.03, 0.5P	PAGE 1 OF 1

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